# onsemi

# **<u>MOSFET</u>** – Power, Single N-Channel 60 V, 26.5 mΩ, 20 A

# NVTFS5C680NL

#### Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVTFS5C680NLWF Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

| Parar   | Symbol              | Value                      | Unit                              |                |    |
|---|---------------------|----------------------------|-----------------------------------|----------------|----|
| Drain-to-Source Voltag  | V <sub>DSS</sub>    | 60                         | V                                 |                |    |
| Gate-to-Source Voltage  | э                   |                            | V <sub>GS</sub>                   | ±20            | V  |
| Continuous Drain  |                     | T <sub>C</sub> = 25°C      | ۱ <sub>D</sub>                    | 20             | А  |
| Current R <sub>θJC</sub><br>(Notes 1, 2, 3, 4)                      | Steady              | T <sub>C</sub> = 100°C     |                                   | 14             |    |
| Power Dissipation   | State               | T <sub>C</sub> = 25°C      | PD                                | 20             | W  |
| $R_{\theta JC}$ (Notes 1, 2, 3)                                     |                     | $T_{C} = 100^{\circ}C$     |                                   | 10             |    |
| Continuous Drain  |                     | T <sub>A</sub> = 25°C      | I <sub>D</sub>                    | 7.82           | А  |
| Current R <sub>θJA</sub><br>(Notes 1 & 3, 4)                        | Steady<br>State     | $T_A = 100^{\circ}C$       |                                   | 6.54           |    |
| Power Dissipation   |                     | T <sub>A</sub> = 25°C      | PD                                | 3.0            | W  |
| $R_{\theta JA}$ (Notes 1, 3)  |                     | T <sub>A</sub> = 100°C     |                                   | 2.1            |    |
| Pulsed Drain Current  | T <sub>A</sub> = 25 | °C, t <sub>p</sub> = 10 μs | I <sub>DM</sub>                   | 80             | А  |
| Operating Junction and Storage Temperature                          |                     |                            | T <sub>J</sub> , T <sub>stg</sub> | –55 to<br>+175 | °C |
| Source Current (Body Diode)   |                     |                            | ۱ <sub>S</sub>                    | 17             | А  |
| Single Pulse Drain–to–Source Avalanche Energy ( $I_{L(pk)} = 1 A$ ) |                     |                            | E <sub>AS</sub>                   | 51             | mJ |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s)   |                     |                            | ΤL                                | 260            | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

| Parameter                                   | Symbol          | Value | Unit |
|---|-----------------|-------|------|
| Junction-to-Case - Steady State (Note 3)    | $R_{\theta JC}$ | 7.32  | °C/W |
| Junction-to-Ambient - Steady State (Note 3) | $R_{\theta JA}$ | 49    |      |

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

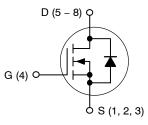
 Psi (Ψ) is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
 Surface, mounted on EP4 heard using a 650 mm<sup>2</sup> 2 or Cu and

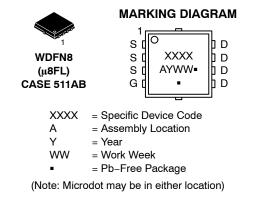
3. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

4. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

| V <sub>(BR)DSS</sub> | R <sub>DS(on)</sub> MAX | I <sub>D</sub> MAX |
|----------------------|-------------------------|--------------------|
| 60 V                 | 26.5 mΩ @ 10 V          | 20 A               |
|                      | 42.5 mΩ @ 4.5 V         | 20 A               |

N-Channel





#### **ORDERING INFORMATION**

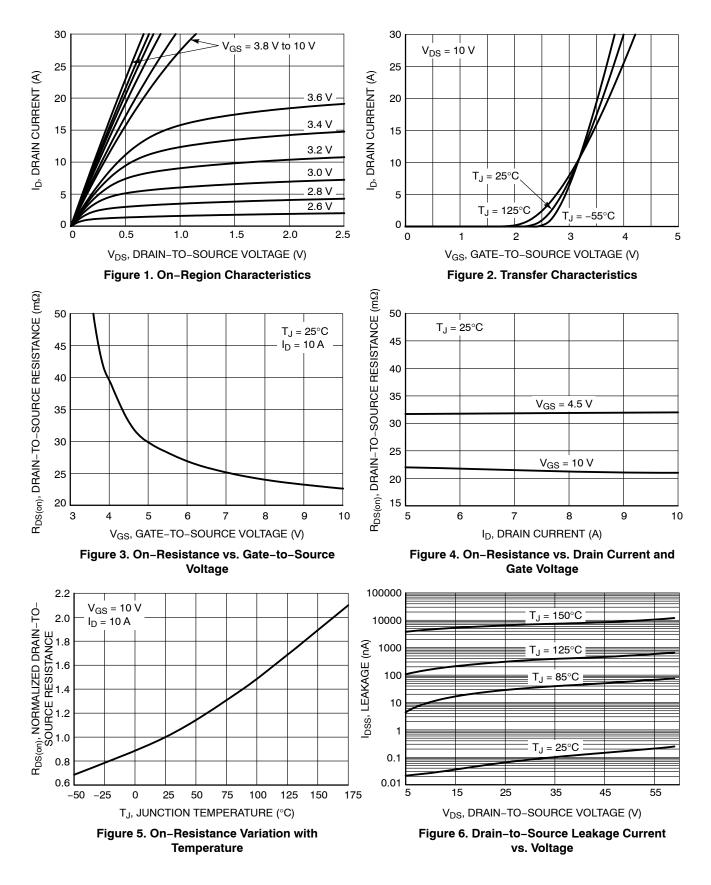
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

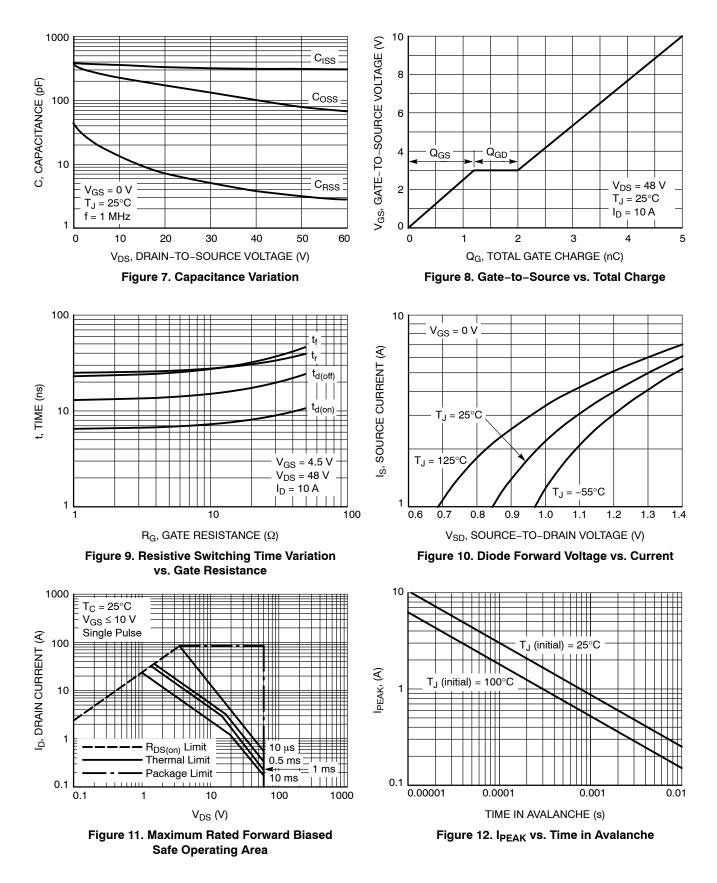
| Parameter                         | Symbol               | Test Condition   |   | Min | Тур | Max  | Unit |  |
|-----------------------------------|----------------------|--|---|-----|-----|------|------|--|
| OFF CHARACTERISTICS               |                      | •  |   |     |     |      |      |  |
| Drain-to-Source Breakdown Voltage | V <sub>(BR)DSS</sub> | $V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A  |   | 60  |     |      | V    |  |
| Zero Gate Voltage Drain Current   | I <sub>DSS</sub>     | V <sub>GS</sub> = 0 V,   | $T_J = 25^{\circ}C$                           |     |     | 10   | μA   |  |
|                                   |                      | $V_{DS} = 60 \text{ V}$  | T <sub>J</sub> = 125°C                        |     |     | 100  |      |  |
| Gate-to-Source Leakage Current    | I <sub>GSS</sub>     | $V_{DS} = 0 V, V_{GS}$   | <sub>S</sub> = +20 V                          |     |     | 100  | nA   |  |
| ON CHARACTERISTICS (Note 5)       |                      |  |   |     |     |      |      |  |
| Gate Threshold Voltage            | V <sub>GS(TH)</sub>  | $V_{GS} = V_{DS}, I_{DS}$  | <sub>0</sub> = 13 μA                          | 1.2 |     | 2.2  | V    |  |
| Drain-to-Source On Resistance     | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A |     | 22  | 26.5 | mΩ   |  |
|                                   |                      | V <sub>GS</sub> = 4.5 V,   | <sub>D</sub> = 10 A                           |     | 34  | 42.5 | 1    |  |
| Forward Transconductance          | 9 <sub>FS</sub>      | V <sub>DS</sub> = 15 V, I  | <sub>D</sub> = 10 A                           |     | 20  |      | S    |  |
| CHARGES AND CAPACITANCES          | -                    | -  |   |     | -   | -    | -    |  |
| Input Capacitance                 | C <sub>iss</sub>     | V <sub>GS</sub> = 0 V, f = 1.0 MHz,<br>V <sub>DS</sub> = 25 V  |   |     | 327 |      | pF   |  |
| Output Capacitance                | C <sub>oss</sub>     |  |   |     | 161 |      |      |  |
| Reverse Transfer Capacitance      | C <sub>rss</sub>     |  |   |     | 6.0 |      |      |  |
| Total Gate Charge                 | Q <sub>G(TOT)</sub>  | $V_{GS}$ = 4.5 V, $V_{DS}$ = 48 V, $I_{D}$ = 10 A  |   |     | 2.9 |      | nC   |  |
| Threshold Gate Charge             | Q <sub>G(TH)</sub>   |  |   |     | 0.8 |      | nC   |  |
| Gate-to-Source Charge             | Q <sub>GS</sub>      |  |   |     | 1.2 |      | 1    |  |
| Gate-to-Drain Charge              | Q <sub>GD</sub>      |  |   |     | 0.8 |      | 1    |  |
| Total Gate Charge                 | Q <sub>G(TOT)</sub>  | V <sub>GS</sub> = 10 V, V <sub>DS</sub> =  | 48 V, I <sub>D</sub> = 10 A                   |     | 6.0 |      | nC   |  |
| SWITCHING CHARACTERISTICS (No     | te 6)                |  |   |     |     |      |      |  |
| Turn-On Delay Time                | t <sub>d(on)</sub>   |  |   |     | 6.5 |      | ns   |  |
| Rise Time                         | t <sub>r</sub>       | V <sub>GS</sub> = 4.5 V. Vr  | ns = 48 V.                                    |     | 25  |      | 1    |  |
| Turn-Off Delay Time               | t <sub>d(off)</sub>  | $\begin{array}{l} V_{GS} = 4.5 \; V, V_{DS} = 48 \; V, \\ I_{D} = 10 \; A, \; R_{G} = 1.0 \; \Omega \end{array}$ |   |     | 13  |      | 1    |  |
| Fall Time                         | t <sub>f</sub>       |  |   |     | 23  |      | 1    |  |
| DRAIN-SOURCE DIODE CHARACTER      | ISTICS               |  |   |     |     |      |      |  |
| Forward Diode Voltage             | V <sub>SD</sub>      | $V_{GS} = 0 V,$<br>$I_{S} = 10 A$  | $T_J = 25^{\circ}C$                           |     | 0.9 | 1.2  | V    |  |
|                                   |                      |  | T <sub>J</sub> = 125°C                        |     | 0.8 |      | 1    |  |
| Reverse Recovery Time             | t <sub>RR</sub>      |  |   |     | 17  |      | ns   |  |
| Charge Time                       | t <sub>a</sub>       | V <sub>GS</sub> = 0 V, dl <sub>S</sub> /dt = 100 A/µs,<br>I <sub>S</sub> = 10 A                                  |   |     | 8.0 |      | 1    |  |
| Discharge Time                    | t <sub>b</sub>       |  |   |     | 9.0 |      | 1    |  |
| Reverse Recovery Charge           | Q <sub>RR</sub>      |  |   |     | 7.0 |      | nC   |  |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
5. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



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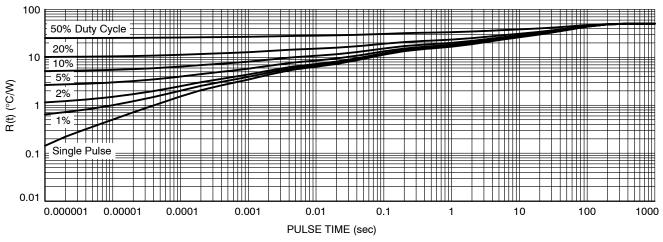


Figure 13. Thermal Characteristics

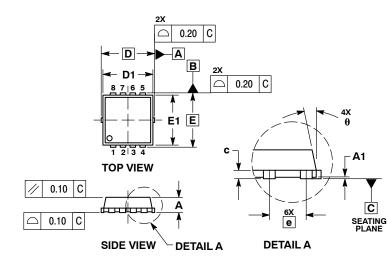
#### **DEVICE ORDERING INFORMATION**

| Device                                   | Marking | Package            | Shipping <sup>†</sup> |
|--|---------|--------------------|-----------------------|
| NVTFS5C680NLTAG                          | 680L    | WDFN8<br>(Pb-Free) | 1500 / Tape & Reel    |
| NVTFS5C680NLWFTAG,<br>NVTFS5C680NLWFETAG | 80LW    | WDFN8<br>(Pb-Free) | 1500 / Tape & Reel    |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

WDFN8 3.3x3.3, 0.65P CASE 511AB **ISSUE D** 



8X k С A 0.10 В ŧ 0.05 С e/2 4X E2 F3 м V D2 G-**BOTTOM VIEW** 

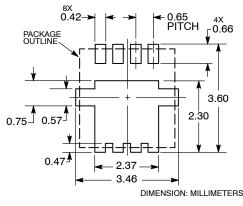
NOTES:

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.

DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS. З.

|     | MILLIMETERS |          |      | INCHES    |       |       |  |
|-----|-------------|----------|------|-----------|-------|-------|--|
| DIM | MIN         | NOM      | MAX  | MIN       | NOM   | MAX   |  |
| Α   | 0.70        | 0.75     | 0.80 | 0.028     | 0.030 | 0.031 |  |
| A1  | 0.00        |          | 0.05 | 0.000     |       | 0.002 |  |
| b   | 0.23        | 0.30     | 0.40 | 0.009     | 0.012 | 0.016 |  |
| с   | 0.15        | 0.20     | 0.25 | 0.006     | 0.008 | 0.010 |  |
| D   | 3.30 BSC    |          |      | 0.130 BSC |       |       |  |
| D1  | 2.95        | 3.05     | 3.15 | 0.116     | 0.120 | 0.124 |  |
| D2  | 1.98        | 2.11     | 2.24 | 0.078     | 0.083 | 0.088 |  |
| Е   | 3.30 BSC    |          |      | 0.130 BSC |       |       |  |
| E1  | 2.95        | 3.05     | 3.15 | 0.116     | 0.120 | 0.124 |  |
| E2  | 1.47        | 1.60     | 1.73 | 0.058     | 0.063 | 0.068 |  |
| E3  | 0.23        | 0.30     | 0.40 | 0.009     | 0.012 | 0.016 |  |
| е   |             | 0.65 BSC | ;    | 0.026 BSC |       |       |  |
| G   | 0.30        | 0.41     | 0.51 | 0.012     | 0.016 | 0.020 |  |
| к   | 0.65        | 0.80     | 0.95 | 0.026     | 0.032 | 0.037 |  |
| L   | 0.30        | 0.43     | 0.56 | 0.012     | 0.017 | 0.022 |  |
| L1  | 0.06        | 0.13     | 0.20 | 0.002     | 0.005 | 0.008 |  |
| М   | 1.40        | 1.50     | 1.60 | 0.055     | 0.059 | 0.063 |  |
| θ   | 0 °         |          | 12 ° | 0 °       |       | 12 °  |  |

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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